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(54) MOUNTING STRUCTURE OF ELECTRONIC PART, ELECTRONIC PART MODULE AND MOUNTING METHOD OF ELECTRONIC PART

(57)Abstract:

PROBLEM TO BE SOLVED: To provide a mounting structure, an electronic part module and a mounting method of an electronic part which are capable of protecting a bump without pouring any under-fill resin between the electronic part and a circuit substrate while being capable of coping with the narrowing of a pitch between bumps.

SOLUTION: An IC chip 8 is arranged on the opposite side of a side, in which pads 93, on which Au platings are applied, are formed in the circuit substrate 9 while being aligned so that bumps 81, on which Au or Sn platings are applied, are superposed on the pads 93. Next, the IC chip 8 is pressed against the circuit substrate 9 while being heated to a temperature higher than the melting temperature of the substrate 91 composed of a thermoplastic resin and lower than the melting temperature of the bumps 81 or 200-300°C, for example. As a result, the substrate 91 is molten whereby the bumps 81 are sunken into the substrate 91 and an alloy junction between the pad 93 and the pad 93 can be effected.

